



# Electronic Filing System (EFS) Data

## Electronic Patent Application Submission

### USPTO Use Only

EFS ID: 50998  
Application ID: 10616044   
Title of Invention: ANOLYTE FOR COPPER PLATING  
First Named Inventor: MICHAEL YANG  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-07-08  
Effective Receipt Date: 2003-11-20  
Submission Type: Information Disclosure Statement  
Filing Type:  
Confirmation number: 9799  
Attorney Docket Number: AMAT7669P2  
  
Total Fees Authorized: 180.0  
Payment Category: Deposit Account  
Deposit Account Number: 200782  
Deposit Account Name: N. ALEXANDER NOLTE  
Access Code: \*\*\*\*  
RAM Payment Status: RAM success  
RAM User ID: EFSPROD  
RAM Accounting Date: 2003-11-20  
RAM Sequence Number: 7

Digital Certificate Holder: cn=N. Alexander Nolte,ou=Registered Attorneys,ou=Patent and Trademark Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 356ec1f20a3e1f2bacfb9b13ed71cf5e5478f58b



## TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	ANOLYTE FOR COPPER PLATING	
Application Number:	10/616044	
Date:	2003-07-08	
First Named Applicant:	Mr. MICHAEL X. YANG	
Confirmation Number:	9799	
Attorney Docket Number:	AMAT7669P2	
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>		
Submitted by:	Elec. Sign.	Sign. Capacity
Mr. N. ALEXANDER NOLTE Registered Number: 45689	[N. ALEXANDER NOLTE]	Attorney
Documents being submitted	Files	
us-ids	AMAT7669P2NAN-usidst.xml	
	us-ids.dtd	
	us-ids.xsl	
us-fee-sheet	AMAT7669P2NAN-usfees.xml	
	us-fee-sheet.xsl	
	us-fee-sheet.dtd	

**Comments**



## FEE TRANSMITTAL

Electronic Version v08  
Stylesheet Version v08.0

Title of Invention	ANOLYTE FOR COPPER PLATING		
Application Number:	10/616044 		
Date:	2003-07-08		
First Named Applicant:	Mr. MICHAEL X. YANG		
Attorney Docket Number:	AMAT7669P2		
Art Unit:	1753		
<b>TOTAL FEE AUTHORIZED \$180</b>			
Patent fees are subject to annual revisions on or about October 1st of each year.			
<b>BASIC FILING FEE</b>			
Fee Description	Fee Code	Amount \$	Fee Paid \$
Submission Of Information Disclosure Stmt Fee	1806	180	180
<b>AUTHORIZED BILLING INFORMATION</b>			
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:			
Deposit account number:	200782		
Access Code	*****		
Deposit name:	Moser Patterson Sheridan		
Deposit authorized name:	N. ALEXANDER NOLTE		
Signature:	/N. ALEXANDER NOLTE/		
Date (YYYYMMDD):	2003-11-20		



## FEE TRANSMITTAL

Electronic Version v08  
Stylesheet Version v08.0

Title of Invention	ANOLYTE FOR COPPER PLATING		
Application Number:	10/616044		
Date:	2003-07-08		
First Named Applicant:	Mr. MICHAEL X. YANG		
Attorney Docket Number:	AMAT7669P2		
Art Unit:	1753		
<b>TOTAL FEE AUTHORIZED \$180</b>			
Patent fees are subject to annual revisions on or about October 1st of each year.			
<b>BASIC FILING FEE</b>			
Fee Description	Fee Code	Amount \$	Fee Paid \$
Submission Of Information Disclosure Stmt Fee	1806	180	180
<b>AUTHORIZED BILLING INFORMATION</b>			
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:			
Deposit account number:	200782		
Access Code	*****		
Deposit name:	Moser Patterson Sheridan		
Deposit authorized name:	N. ALEXANDER NOLTE		
Signature:	/N. ALEXANDER NOLTE/		
Date (YYYYMMDD):	2003-11-20		



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	ANOLYTE FOR COPPER PLATING				
Application Number:	10/616044 				
Confirmation Number:	9799				
First Named Applicant:	MICHAEL YANG				
Attorney Docket Number:	AMAT7669P2				
Art Unit:	1753				
Search string:	( 5224504 or 5489341 or 5573023 or 5620581 or 5731678 or 5744019 or 5837120 or 5883762 or 5996241 or 6014817 or 6099702 or 6099712 or 6126798 or 6132857 or 6136163 or 6156167 or 6179983 or 6228231 or 6228232 or 6248222 or 6254742 or 6261433 or 6267853 or 6273110 or 6280582 or 6322674 or 6322678 or 6368475 or 6374837 or 6383352 or 6391166 or 6395101 or 6395152 or 6409892 or 6432821 or 6436249 or 6440295 or 6527920 or 6551487 or 6569299 or 6589401 or 5252196 or 6197181 or 6290833 or 6319387 or 6334937 or 6551479 or 20020074233 ).pn.				
US Patent Documents					
Note: Applicant is not required to submit a paper copy of cited US Patent Documents					
init	Cite.No.	Patent No.	Date	Patentee	Kind
	1	5224504	1993-07-06	THOMPSON, ET AL.	Class
	2	5489341	1996-02-06	BERGMAN, ET AL.	Subclass
	3	5573023	1996-11-12	THOMPSON, ET AL.	
	4	5620581	1997-04-15	ANG	
	5	5731678	1998-03-24	ZILA, ET AL.	
	6	5744019	1998-04-28	ANG	
	7	5837120	1998-11-17	FORAND, ET AL.	
	8	5883762	1999-03-16	CALHOUN, ET AL.	
	9	5996241	1999-12-07	THOMPSON, ET AL.	
	10	6014817	2000-01-18	THOMPSON, ET AL.	

	11	6099702	2000-08-08	REID, ET AL.
	12	6099712	2000-08-08	RITZDORF, ET AL.
	13	6126798	2000-10-03	REID, ET AL.
	14	6132857	2000-10-17	CHAMPENOIS, ET AL.
	15	6136163	2000-10-24	CHEUNG, ET AL.
	16	6156167	2000-12-05	PATTON, ET AL.
	17	6179983	2001-01-30	REID, ET AL.
	18	6228231	2001-05-08	UZOH
	19	6228232	2001-05-08	WOODRUFF, ET AL.
	20	6248222	2001-06-19	WANG
	21	6254742	2001-07-03	HANSON, ET AL.
	22	6261433	2001-07-17	LANDAU
	23	6267853	2001-07-31	DORDI, ET AL.
	24	6273110	2001-08-14	DAVIS, ET AL.
	25	6280582	2001-08-28	WOODRUFF, ET AL.
	26	6322674	2001-11-27	BERNER, ET AL.
	27	6322678	2001-11-27	WOODRUFF, ET AL.
	28	6368475	2002-04-09	HANSON, ET AL.
	29	6374837	2002-04-23	SCRANTON, ET AL.
	30	6383352	2002-05-07	SHYU, ET AL.
	31	6391166	2002-05-21	WANG
	32	6395101	2002-05-28	SCRANTON, ET AL.
	33	6395152	2002-05-28	WANG
	34	6409892	2002-06-25	WOODRUFF, ET AL.
	35	6432821	2002-08-13	DUBIN, ET AL.
	36	6436249	2002-08-20	PATTON, ET AL.
	37	6440295	2002-08-27	WANG
	38	6527920	2003-03-04	MAYER, ET AL.
	39	6551487	2003-04-22	REID, ET AL.
	40	6569299	2003-05-27	REID, ET AL.
	41	6589401	2003-07-08	PATTON, ET AL.
	42	5252196	1993-10-12	SONNENBERG, ET AL.
	43	6197181	2001-03-06	CHEN
	44	6290833	2001-09-18	CHEN
	45	6319387	2001-11-20	KRISHNAMOORTHY, ET AL.
	46	6334937	2001-01-01	BATZ, JR, ET AL.

	47	6551479	2003-04-22	GRAHAM, ET AL.
--	----	---------	------------	----------------

## US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
	1	20020074233	2002-06-20	RITZDORF, ET AL.			

## Signature

Examiner Name	Date